

# TITLE OF THE INVENTION

ASYNCHRONOUS PSEUDO SRAM

## CROSS-REFERENCE TO RELATED APPLICATIONS

This application is based upon and claims the  
5 benefit of priority from the prior Japanese Patent  
Application No. 2003-338528, filed September 29, 2003,  
the entire contents of which are incorporated herein by  
reference.

## BACKGROUND OF THE INVENTION

### 10 1. Field of the Invention

The present invention relates to a semiconductor  
integrated circuit device and, more particularly, to an  
asynchronous pseudo SRAM which uses a DRAM (Dynamic  
Random Access Memory) or ferroelectric memory in the  
15 memory core portion.

### 2. Description of the Related Art

Pseudo SRAMs are commercially available, which use  
a DRAM or ferroelectric memory in the memory core  
portion to increase the degree of integration while  
20 maintaining use compatibility to existing SRAMs.  
The mainstream of conventional pseudo SRAMs is a  
synchronous type which controls the operations of  
internal circuits by a clock signal (internal circuit  
control signal) time-serially generated in the device  
25 from an external input signal, e.g., an external chip  
enable signal /CE, as shown in FIGS. 1A and 1B.

In recent years, a demand for pseudo SRAMs

oriented for cellular phones is increasing.  
Especially, a demand for asynchronous pseudo SRAMs  
which operate even asynchronously to an external input  
signal is growing.

5           To implement an asynchronous pseudo SRAM, an  
operation as shown in the timing charts of FIGS. 2A and  
2B is necessary. FIG. 2A shows a read operation.  
FIG. 2B shows a write operation. To realize the read  
and write operations shown in FIGS. 2A and 2B, for  
10       example, an arrangement shown in FIG. 3 can be used.  
More specifically, a plurality of address transition  
detection circuits (row/column system ATDs 100) which  
detect address transition are prepared. A row address  
signal ADx output from a row address buffer circuit 101  
15       and a column address signal ADy output from a column  
address buffer circuit 102 are supplied to the  
row/column system ATD 100, thereby detecting the  
transition of row and column addresses. On the basis  
of an AND signal ATDSUM of the detection result by the  
20       row/column system ATD 100, an internal CE control  
circuit 103 generates an internal chip enable signal  
(internal circuit control signal) INCE to control the  
internal circuits. The internal chip enable signal  
INCE is supplied to a row system circuit 104 and column  
25       system circuit 105. Signals that time-serially drive a  
word line WL and plate line PL in a memory cell array  
106 are generated to control the data read and write

(Dout and Din) operations.

In this arrangement, the cycle time defined by the external input signals (external chip enable signal /CE and address signals ADx and ADy) can freely be set.

5       However, the internal chip enable signal INCE used to control the operations of the internal circuits has a predetermined cycle time because the signal is generated by using a timeout circuit (with constant time).

10           A proposal has been made in which the above-described restriction on the write operation should be eliminated by executing read and write operations as shown in the timing charts of FIGS. 4A and 4B. More specifically, in the read operation, the  
15       internal chip enable signal INCE (auto pulse) is generated by using a timeout circuit, as shown in FIG. 4A. In the write operation, the operations of the internal circuits are controlled by an external write enable signal /WE, as shown in FIG. 4B, without using  
20       any timeout circuit.

          Additionally, asynchronous pseudo SRAMs often have a high-speed operation mode such as a static column mode in which the memory cells of a row selected by a row address are sequentially accessed by a column  
25       address signal, as shown in FIG. 1B.

          However, the conventional pseudo SRAM cannot execute the high-speed operation mode such as a static

column mode while operating asynchronously to  
an external input signal. This is because an  
asynchronous pseudo SRAM cannot discriminate between  
row access that is triggered by the transition of row  
5 and column addresses and column access that is also  
triggered by the transition of a column address. In  
addition, since the asynchronous pseudo SRAM controls  
the operations of the internal circuits by using a  
timeout circuit, the cycle time of the internal  
10 circuits is constant. That is, the arrangement is not  
compatible to a special operation mode.

Hence, there is a demand for implementation of a  
semiconductor integrated circuit device which can  
operate a pseudo SRAM asynchronously to an external  
15 input signal and also asynchronously execute a  
high-speed operation mode.

To meet this demand, for example, Jpn. Pat. Appln.  
KOKAI Publication No. 2002-269977 discloses the  
following arrangement. Two ATDs for row access and  
20 column access are prepared. In addition, a mode  
determination circuit is arranged, which generates an  
internal circuit control signal having a desired length  
necessary for access on the basis of the ATDs and  
determines two modes. The mode is automatically  
25 determined on the basis of the interval of address  
transition.

In the arrangement disclosed in this prior art,

however, the address transition interval detection time must be set within a predetermined range. The cycle time of the column access mode cannot freely be set.

#### BRIEF SUMMARY OF THE INVENTION

5           According to an aspect of the present invention, there is provided a semiconductor integrated circuit device comprising a memory cell array, a chip enable transition detection circuit which detects transition of a chip enable signal that indicates a start of an  
10           operation of the memory cell array, a first address transition detection circuit which detects transition of a row address signal that indicates a row address of the memory cell array and transition of a column  
15           address signal that indicates a column address, a write enable transition detection circuit which detects transition of a write enable signal that indicates a write operation of the memory cell array, a first  
20           control circuit comprising a timeout circuit which generates a control signal that controls row access of the memory cell array on the basis of detection results of the chip enable transition detection circuit, the  
25           first address transition detection circuit, and the write enable transition detection circuit, a second address transition detection circuit which detects only the transition of the column address signal, a second  
            control circuit which controls column access of the memory cell array on the basis of a detection result of

the second address transition detection circuit, and a mode determination circuit which determines a start of a mode in which column access is executed and generates a mode determination signal when a condition that  
5 allows a start of a column access operation of the memory cell array is satisfied, and the second address transition detection circuit detects the transition of the column address, or determines an end of column access and sets a standby state when column access  
10 starts, and transition of a predetermined address or a row address is detected, wherein when the mode determination circuit determines row access, the access operation of the memory cell array is controlled by the timeout circuit in the first control circuit in read  
15 and write operations for the memory cell array, and when the mode determination circuit determines column access, an active operation is continued while stopping control by the timeout circuit until column access is ended in the read and write operations for the memory  
20 cell array.

According to another aspect of the present invention, there is provided a semiconductor integrated circuit device comprising a memory cell array, a chip enable transition detection circuit which detects  
25 transition of a chip enable signal that indicates a start of an operation of the memory cell array, a first address transition detection circuit which detects

transition of a row address signal that indicates a row  
address of the memory cell array and transition of a  
column address signal that indicates a column address,  
a write enable transition detection circuit which  
5 detects transition of a write enable signal that  
indicates a write operation of the memory cell array, a  
first control circuit comprising a timeout circuit  
which generates a control signal that controls row  
access of the memory cell array on the basis of  
10 detection results of the chip enable transition  
detection circuit, the first address transition  
detection circuit, and the write enable transition  
detection circuit, a second address transition  
detection circuit which detects only the transition of  
15 the column address signal, a second control circuit  
which controls column access of the memory cell array  
on the basis of a detection result of the second  
address transition detection circuit, and a mode  
determination circuit which determines a start of a  
20 mode in which column access is executed and generates a  
mode determination signal when a condition that allows  
a start of a column access operation of the memory cell  
array is satisfied, and the second address transition  
detection circuit detects the transition of the column  
25 address, or determines an end of column access and sets  
a standby state when column access starts, and  
transition of a predetermined address or a row address

is detected, wherein when the mode determination circuit determines row access, the access operation of the memory cell array is controlled by the timeout circuit in the first control circuit in read and write operations for the memory cell array, in the write operation for the memory cell array, when the write enable transition detection circuit detects the transition of an end of the write enable signal before a period indicated by the timeout circuit, the access operation of the memory cell array is controlled by the timeout circuit, in the write operation for the memory cell array, when the write enable transition detection circuit detects the transition of the end of the write enable signal after the period indicated by the timeout circuit, the access operation of the memory cell array is controlled in response to the transition of the write enable signal, when the mode determination circuit determines column access, an active operation is continued while stopping control by the timeout circuit until column access is ended in the read operation for the memory cell array, and in the write operation for the memory cell array, the active operation is continued while stopping control by the timeout circuit or control that responds to the transition of the write enable signal until column access is ended.



BRIEF DESCRIPTION OF THE SEVERAL VIEWS OF THE DRAWING

FIG. 1A is a timing chart showing the normal read operation of a synchronous pseudo SRAM so as to explain a conventional semiconductor integrated circuit device;

5        FIG. 1B is a timing chart showing the static column read operation of the synchronous pseudo SRAM so as to explain the conventional semiconductor integrated circuit device;

FIG. 2A is a timing chart of a semiconductor  
10 integrated circuit device which uses a timeout circuit for both the read and write operations, which shows the read operation of an asynchronous pseudo SRAM so as to explain a conventional semiconductor integrated circuit device;

15        FIG. 2B is a timing chart of the semiconductor integrated circuit device which uses a timeout circuit for both the read and write operations, which shows the write operation of the asynchronous pseudo SRAM so as to explain the conventional semiconductor integrated  
20 circuit device;

FIG. 3 is a block diagram showing a circuit  
section related to the read and write in the  
asynchronous pseudo SRAM incorporated in the  
semiconductor integrated circuit device so as to  
25 explain the conventional semiconductor integrated circuit device;

FIG. 4A is a timing chart of a semiconductor

integrated circuit device which uses a timeout circuit  
for only the read operation and controls the write  
operation on the basis of an external WE signal, which  
shows the read operation of an asynchronous pseudo SRAM  
so as to explain a conventional semiconductor  
integrated circuit device;

FIG. 4B is a timing chart of the semiconductor  
integrated circuit device which uses a timeout circuit  
for only the read operation and controls the write  
operation on the basis of an external WE signal, which  
shows the write operation of the asynchronous pseudo  
SRAM so as to explain the conventional semiconductor  
integrated circuit device;

FIG. 5 is a schematic block diagram showing  
circuits related to the read and write of a pseudo SRAM  
incorporated in a semiconductor integrated circuit  
device so as to explain a semiconductor integrated  
circuit device according to the first embodiment of the  
present invention;

FIG. 6 is a block diagram showing the detailed  
arrangement of the main part of the circuits shown in  
FIG. 5 and details of peripheral circuits;

FIG. 7A is an equivalent circuit diagram showing a  
ferroelectric cell having a 1-transistor/1-capacitor  
structure so as to explain the structure of the memory  
cell array shown in FIG. 6;

FIG. 7B is a timing chart showing the operation

waveforms of the ferroelectric cell shown in FIG. 7A;

FIG. 8 is a graph showing the relationship  
(hysteresis characteristic) between the applied voltage  
and the remnant polarization of the ferroelectric cell  
shown in FIG. 7A;

FIG. 9 is a circuit diagram showing the detailed  
arrangement of an internal CE control circuit so as to  
explain the operation of the semiconductor integrated  
circuit device shown in FIGS. 5, 6, and 7A;

FIG. 10A is a timing chart showing a normal read  
operation so as to explain the read operation of the  
internal CE control circuit shown in FIG. 9;

FIG. 10B is a timing chart showing a static column  
read operation so as to explain the read operation of  
the internal CE control circuit shown in FIG. 9;

FIG. 11A is a timing chart showing a normal write  
operation so as to explain the write operation of the  
internal CE control circuit shown in FIG. 9;

FIG. 11B is a timing chart showing a static column  
write operation so as to explain the write operation of  
the internal CE control circuit shown in FIG. 9;

FIG. 12 is a circuit diagram showing the detailed  
arrangement of a mode determination circuit so as to  
explain the operation of the semiconductor integrated  
circuit device shown in FIGS. 5, 6, and 7A;

FIG. 13 is a timing chart showing the operation of  
the mode determination circuit shown in FIG. 12;

FIG. 14A is a timing chart showing a static column read operation so as to explain the operation of the semiconductor integrated circuit device shown in FIGS. 5, 6, and 7A;

5           FIG. 14B is a timing chart showing a static column write operation so as to explain the operation of the semiconductor integrated circuit device shown in FIGS. 5, 6, and 7A;

10           FIG. 15A is a timing chart showing a static column read operation so as to explain another operation of the semiconductor integrated circuit device shown in FIGS. 5, 6, and 7A;

15           FIG. 15B is a timing chart showing a static column write operation so as to explain another operation of the semiconductor integrated circuit device shown in FIGS. 5, 6, and 7A;

20           FIG. 16 is a block diagram showing the detailed arrangement of a main part related to the read and write of a pseudo SRAM so as to explain a semiconductor integrated circuit device according to the second embodiment of the present invention;

25           FIG. 17 is a timing chart showing the delayed normal write operation of the pseudo SRAM shown in FIG. 16 so as to explain the semiconductor integrated circuit device according to the second embodiment of the present invention;

FIG. 18 is a timing chart showing the delayed

static column write operation of the pseudo SRAM shown in FIG. 16 so as to explain the semiconductor integrated circuit device according to the second embodiment of the present invention;

5           FIG. 19 is a block diagram showing the detailed arrangement of a main part related to the read and write of a pseudo SRAM so as to explain a semiconductor integrated circuit device according to the third embodiment of the present invention;

10           FIG. 20A is an equivalent circuit diagram showing one unit of TC parallel unit series-connected ferroelectric cells so as to explain a semiconductor integrated circuit device according to the fourth embodiment of the present invention;

15           FIG. 20B is a timing chart showing the operation waveforms of the ferroelectric cell shown in FIG. 20A;

            FIG. 21A is an equivalent circuit diagram showing a DRAM cell so as to explain a semiconductor integrated circuit device according to the fifth embodiment of the present invention;

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            FIG. 21B is a timing chart showing the operation waveforms of the DRAM cell shown in FIG. 21A;

            FIG. 22 is a block diagram showing the DSL (Digital Subscriber Line) data path portion of a DSL modem so as to explain Application Example 1 of the semiconductor integrated circuit devices (pseudo SRAMs) according to the first to fourth embodiments of the

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present invention;

FIG. 23 is a block diagram showing a cellular phone terminal so as to explain Application Example 2 of the semiconductor integrated circuit devices (pseudo SRAMs) according to the first to fourth embodiments of the present invention; and

FIG. 24 is a plan view showing an example in which a pseudo SRAM is applied to a card such as a smart medium which stores media contents so as to explain Application Example 3 of the semiconductor integrated circuit devices (pseudo SRAMs) according to the first to fourth embodiments of the present invention.

#### DETAILED DESCRIPTION OF THE INVENTION

##### [First Embodiment]

FIG. 5 is a schematic block diagram showing circuits related to the read and write of a pseudo SRAM incorporated in a semiconductor integrated circuit device so as to explain a semiconductor integrated circuit device according to the first embodiment of the present invention. The pseudo SRAM comprises an internal CE control circuit 1, CE buffer circuit 2a, row address buffer circuit 2b, column address buffer circuit 2c, WE buffer circuit 2d, internal WE control circuit 6, column system ATD 10, row/column system ATD 11, row system circuit 12, column system circuit 13, memory cell array 15, and mode determination circuit 26.

An external chip enable signal /CE is input to the CE buffer circuit 2a. A row address signal ADx is input to the row address buffer circuit 2b. A column address signal ADy is input to the column address buffer circuit 2c. An external write enable signal /WE is input to the WE buffer circuit 2d. Output signals from the buffer circuits 2a to 2d are supplied to the row/column system ATD 11. An output signal from the buffer circuit 2c is supplied to the column system ATD 10. The column system ATD 10 detects the transition of the column address signal ADy and generates a detection signal (ATD signal) ATDSC necessary for the operation of the column system circuit 13. The output signal from the buffer circuit 2d is supplied to the internal WE control circuit 6.

A mode determination signal SC output from the mode determination circuit 26 is supplied to the row/column system ATD 11. A row/column system detection signal (ATD signal) ATDSUM is supplied to the internal CE control circuit 1. An output signal from the CE buffer circuit 2a and the mode determination signal SC output from the mode determination circuit 26 are supplied to the internal CE control circuit 1. The internal CE control circuit 1 generates an internal chip enable signal INCE to control the operation of the row system circuit 12 and column system circuit 13 and also control the row address buffer circuit 2b, column

address buffer circuit 2c, and internal WE control circuit 6.

5 A mode address (row address) is supplied from the buffer circuits 2b and 2c to the mode determination circuit 26. A sense amplifier enable signal SAEBL from the row system circuit 12 and the ATD signal ATDSC from the column system ATD 10 are also supplied to the mode determination circuit 26. The mode determination circuit 26 determines on the basis of these signals  
10 which of row access and column access should be executed and generates the mode determination signal SC.

The sense amplifier enable signal SAEBL output from the row system circuit 12 and the mode  
15 determination signal SC output from the mode determination circuit 26 are supplied to the column system ATD 10. The column system ATD 10 supplies the ATD signal ATDSC of a column address to the column system circuit 13.

20 An output signal (internal write enable signal) INWE from the internal WE control circuit 6 is also supplied to the column system circuit 13.

The access operation to the memory cell array 15 is executed by the row system circuit 12 and column  
25 system circuit 13. Then, read data Dout is output from the memory cell array 15. Alternatively, write data Din is input to the memory cell array 15.



FIG. 6 is a block diagram showing the detailed arrangement of the main part of the circuits shown in FIG. 5 and details of peripheral circuits. The row/column system ATD 11 includes an ATD circuit 3, AND circuit 4, and trigger delay ON/OFF circuit 24. The ATD circuit 3 is constructed by ATDs 3a to 3d which receive the output signals from the buffer circuits 2a to 2d and detect the transition of these signals. Signals ATDCE, ATDADy, and ATDWE representing the detection results output from the ATDs 3a, 3c, and 3d are supplied to the input terminals of the AND circuit 4. A signal ATDADx representing the detection result output from the ATD 3b is supplied to the AND circuit 4 through the trigger delay ON/OFF circuit 24. A control signal CYCLE that is output from the internal CE control circuit 1 to define the cycle is supplied to the trigger delay ON/OFF circuit 24 to control it. The trigger delay ON/OFF circuit 24 is used to receive the transition trigger of the row address signal ADx not within the cycle but after the end of the cycle. The AND signal ATDSUM output from the AND circuit 4 is supplied to the internal CE control circuit 1.

The output signals from the buffer circuits 2a and 2d are supplied to the input terminals of a NOR circuit 5. The NOR circuit 5 supplies, to the internal WE control circuit 6, a signal WEEBL to start a write operation when both the external chip enable signal /CE

and the external write enable signal /WE are at "L" level.

5       The internal CE control circuit 1 includes a switch (SW) 1C, a pulse generator (Auto pulse) 1A which serves as an internal timeout circuit and outputs a pulse having a predetermined width, and a pulse generator (Ext. pulse) 1B which outputs a pulse signal in response to the transition of the external write enable signal /WE in the write operation and in  
10       switching the mode. The AND signal ATDSUM output from the AND circuit 4, the internal write enable signal INWE output from the internal WE control circuit 6, and the mode determination signal SC output from the mode determination circuit 26 are supplied to the switch 1C.  
15       A signal selected by the switch 1C is supplied to the pulse generators 1A and 1B. The internal chip enable signals INCE (INCE1/INCE2) output from the pulse generators 1A and 1B are supplied to a row system control circuit 12' and column system control circuit  
20       13', respectively. The control signal CYCLE that defines the cycle is supplied to the trigger delay ON/OFF circuit 24.

      The row system control circuit 12' controls the row system circuit 12 which includes a plate (PL)  
25       control circuit 7, word line (WL) control circuit 8, row decoder/plate decoder (RD/PD) 14, and sense amplifier control circuit 27.

The column system control circuit 13' controls the column system circuit 13 which includes a column decoder (CD) 16 and DQ buffer 23.

5 An output signal PLCLK from the plate control circuit 7 and an output signal WLCLK from the word line control circuit 8 are supplied to the row decoder/plate decoder 14. The row decoder/plate decoder 14 selects and drives a word line WL and plate line PL in the memory cell array 15. In addition, the sense amplifier  
10 in the memory cell array 15 is driven by the sense amplifier enable signal SAEBL output from the sense amplifier control circuit 27. Furthermore, a column select line CSL in the memory cell array 15 is selected by the column decoder 16.

15 The sense amplifier enable signal SAEBL output from the sense amplifier control circuit 27 is supplied to the mode determination circuit 26. The mode addresses output from the buffer circuits 2b and 2c and the ATD signal ATDSC of a column address, which is  
20 output from the column system ATD 10, are supplied to the mode determination circuit 26 so that it generates the mode determination signal SC to be supplied to the switch 1C.

25 The write data Din to a selected memory cell in the memory cell array 15 is latched by a write data latch 18, supplied to a data latch 22, and written through a data line DQL. The write data Din latched by

the write data latch 18 can be output to the outside.  
On the other hand, data read out from a selected memory  
cell is supplied to the DQ buffer 23 through the data  
line DQL, supplied to and latched by a read data latch  
5 19, and output as the readout data Dout.

The operations of the write data latch 18 and read  
data latch 19 are controlled by an input/output system  
control circuit 17. The input/output system control  
circuit 17 and data latch 22 are controlled by the  
10 internal write enable signal INWE output from the  
internal WE control circuit 6.

Ferroelectric cells MC1 each having a  
1-transistor/1-capacitor structure shown in FIG. 7A are  
arranged in a matrix in the memory cell array 15. In a  
15 cell capacitor C1 of the ferroelectric cell MC1, a  
ferroelectric material such as lead zirconate titanate  
( $\text{PbZrTiO}_3$ : PZT) is used as a capacitor insulating film.

The structure and the data write, read, and  
rewrite operations of the ferroelectric cell MC1 will  
20 be briefly described with reference to FIGS. 7A, 7B,  
and 8.

The data write operation for the ferroelectric  
cell MC1 is executed in the following manner. The word  
line WL is selected. In this state, the plate line PL  
25 is pulse-driven from the ground potential ("L" level)  
to a predetermined potential ("H" level) and then  
returned to "L" level. With this operation, data on a

bit line BL can be written.

In the read operation for data stored in the ferroelectric cell MC1, the word line WL is selected. In this state, the plate line PL is pulse-driven from "L" level to "H" level. With this operation, charges  
5 can be read out to the bit line BL.

More specifically, when no voltage is applied between the electrodes, the cell capacitor C1 of the ferroelectric cell MC1 shown in FIG. 7A has one of  
10 polarization states in two, upward and downward directions indicated by "0" and "1" in FIG. 8. That is, the ferroelectric cell MC1 is a nonvolatile memory. In this state, a voltage is applied. In the state "1", the polarization is not reversed. In the state "0",  
15 the polarization is reversed. The charge amount necessary for applying the same voltage, i.e., the charge amount generated in one electrode in accordance with the "0" or "1" storage state when the same voltage is applied to the other electrode changes between the  
20 two states. Stored data is read out by detecting the difference. The data read from such a ferroelectric memory is a destructive read. A rewrite operation must always be executed after the read operation.

The data rewrite operation for the ferroelectric cell MC1 shown in FIG. 7A will be described. For read  
25 data "0", the rewrite operation of the data "0" is executed when it is sense-amplified by the sense

amplifier in the read mode, as shown in FIG. 7B. To the contrary, for read data "1", the plate line PL is returned from "H" level to "L" level, and the rewrite operation of the data "1" is then started.

5           The reason why mode determination of row access and column access by the mode determination circuit 26 is necessary in the pseudo SRAM shown in FIGS. 5 and 6 will be described next.

10           The row access (normal mode) operation and column access (static column mode) operation in the circuit shown in FIG. 5 do not change until word line selection. Then, the operation changes. In row access, a standby operation is performed a predetermined time after the internal chip enable signal INCE  
15           is generated on the basis of the row/column system ATD signal (ATDSUM). In column access, no standby state is set during the access period. Instead, a standby state is set upon detecting the end of access.

20           For this purpose, the internal CE control circuit 1 is constructed by using, e.g., a pulse generator shown in FIG. 9. The internal CE control circuit 1 includes inverters 30 to 33, delay circuit 34, and NAND circuits 35 and 36. The circuit 1 serves as a pulse generator which calculates the logic between the mode  
25           determination signal SC, the internal write enable signal INWE, and the pulse-shaped AND signal ATDSUM which is generated by using, as a trigger, the

transition of one of the external chip enable signal /CE, external write enable signal /WE, and address signals ADx and ADy.

5       The AND signal ATDSUM output from the row/column system ATD 11 is supplied to the input terminal of the inverter 30. An output signal P1 from the inverter 30 is supplied to one input terminal of the NAND circuit 36 and the delay circuit 34. A delay signal P2 output from the delay circuit 34 is supplied to the first  
10       input terminal of the NAND circuit 35. The mode determination signal SC output from the mode determination circuit 26 is supplied to the input terminal of the inverter 31. An output signal P5 from the inverter 31 is supplied to the second input terminal of  
15       the NAND circuit 35. The internal write enable signal INWE output from the internal WE control circuit 6 is supplied to the input terminal of the inverter 32. An output signal P3 from the inverter 32 is supplied to the third input terminal of the NAND circuit 35. The  
20       output signal from the NAND circuit 35 is supplied to the input terminal of the inverter 33. An output signal P4 from the inverter 33 is supplied to the other input terminal of the NAND circuit 36. The internal chip enable signal INCE is output from the output  
25       terminal of the NAND circuit 36.

      The internal CE control circuit 1 executes the normal read operation as shown in the timing chart of

FIG. 10A. When the row/column system ATD 11 detects the transition of the address signal, and the AND signal ATDSUM changes to "L" level, the output signal P1 from the inverter 30 changes to "H" level. The internal chip enable signal INCE output from the NAND circuit 36 changes to "H" level. The output signal P1 from the inverter 30 is delayed by the delay circuit 34 and supplied to the first input terminal of the NAND circuit 35. At this time, the mode determination signal SC output from the mode determination circuit 26 and the internal write enable signal INWE output from the internal WE control circuit 6 are always at "L" level. For this reason, the output signals P5 and P3 from the inverters 31 and 32 are at "H" level. After the elapse of a predetermined delay time, the output signal P2 from the delay circuit 34 changes from "L" level to "H" level. The output signal from the NAND circuit 35 changes to "L" level. The output signal P4 from the inverter 33 changes to "H" level. As a result, the internal chip enable signal INCE output from the NAND circuit 36 changes to "L" level.

That is, the internal CE control circuit 1 serves as a pulse generator which generates the auto pulse signal INCE that is set at "H" level during the period after the AND signal ATDSUM changes to "L" level until the delay time of the delay circuit 34.

To the contrary, in the static column read



operation shown in FIG. 10B, when the AND signal ATDSUM output from the row/column system ATD 11 changes to "L" level upon detecting the address transition, the output signal P1 from the inverter 30 changes to "H" level.

5 The internal chip enable signal INCE output from the NAND circuit 36 changes to "H" level. The output signal P1 from the inverter 30 is delayed by the delay circuit 34 and supplied to the first input terminal of the NAND circuit 35. During the period when the  
10 mode determination signal SC output from the mode determination circuit 26 and the internal write enable signal INWE output from the internal WE control circuit 6 are at "L" level, the output signals P5 and P3 from the inverters 31 and 32 are at "H" level. The output  
15 signal from the NAND circuit 35 changes to "L" level. The output signal P4 from the inverter 33 changes to "H" level. Hence, the internal chip enable signal INCE output from the NAND circuit 36 maintains "H" level.

The static column read operation starts. When the  
20 mode determination signal SC changes to "H" level within the delay time of the delay circuit 34, the output signal INCE from the internal CE control circuit 1 continuously maintains "H" level, independently of the delay time of the delay circuit 34, during the  
25 period until the mode determination signal SC changes to "L" level. Hence, the internal CE control circuit 1 serves as a pulse generator which generates a pulse

signal (Ext. pulse) that maintains "H" level during the period after the AND signal ATDSUM changes to "L" level until the mode determination signal SC changes to "L" level.

5           FIGS. 11A and 11B are timing charts showing the write operations of the circuit shown in FIG. 9. In the normal write operation, as shown in the timing chart of FIG. 11A, when the transition of an address  
10           the AND signal ATDSUM changes to "L" level, the output signal P1 from the inverter 30 changes to "H" level. The internal chip enable signal INCE output from the NAND circuit 36 changes to "H" level. The output  
15           signal P1 from the inverter 30 is delayed by the delay circuit 34 and supplied to the first input terminal of the NAND circuit 35. At this time, the mode determination signal SC output from the mode determination  
20           circuit 26 is at "L" level. When the external write enable signal /WE changes to "L" level to start the write operation within the delay time of the delay  
25           circuit 34, the internal write enable signal INWE output from the internal WE control circuit 6 changes to "H" level. Hence, the output signal P5 from the inverter 31 is at "H" level. The output signal P3 from the inverter 32 is at "L" level. The output signal  
            from the NAND circuit 35 changes to "L" level. The output signal P4 from the inverter 33 changes to "H"

level. As a result, the internal chip enable signal INCE output from the NAND circuit 36 changes to "L" level independently of the delay time.

That is, the internal CE control circuit 1 serves  
5 as a pulse generator which generates the pulse signal INCE that is set at "H" level during the period after the AND signal ATDSUM changes to "L" level until the internal write enable signal INWE changes to "L" level.

To the contrary, in the static column write  
10 operation shown in FIG. 11B, when the AND signal ATDSUM output from the row/column system ATD 11 changes to "L" level upon detecting the address transition, the output signal P1 from the inverter 30 changes to "H" level. The internal chip enable signal INCE output from the  
15 NAND circuit 36 changes to "H" level. The output signal P1 from the inverter 30 is delayed by the delay circuit 34 and supplied to the first input terminal of the NAND circuit 35. At this time, both the mode determination signal SC output from the mode determi-  
20 nation circuit 26 and the internal write enable signal INWE output from the internal WE control circuit 6 are at "L" level. For this reason, the output signals P5 and P3 from the inverters 31 and 32 are at "H" level. The output signal from the NAND circuit 35 changes to  
25 "L" level. The output signal P4 from the inverter 33 changes to "H" level. Hence, the internal chip enable signal INCE output from the NAND circuit 36 is at "H"

level.

When the mode determination signal SC changes to "H" level within the delay time of the delay circuit 34, the static column write operation starts. The internal write enable signal INWE changes to "H" level. The output signal INCE from the internal CE control circuit 1 continuously maintains "H" level, independently of the delay time of the delay circuit 34, during the period until the mode determination signal SC changes to "H" level. Hence, the internal CE control circuit 1 serves as a pulse generator which generates a pulse signal (Ext. pulse) that maintains "H" level after the AND signal ATDSUM changes to "L" level until the mode determination signal SC changes to "L" level, as in the normal read operation.

Even when cycle operation is started upon detecting not the address transition but the transition of the external write enable signal /WE, the same operation as described above can be executed by the AND signal ATDSUM output from the row/column system ATD 11. That is, the internal chip enable signal INCE in the write operation is controlled not by the internal timeout time but by the external write enable signal /WE.

FIG. 12 shows the detailed arrangement of the mode determination circuit 26 in the circuit shown in FIGS. 5 and 6. The mode determination circuit 26

includes NAND circuits 40 to 44 and an inverter 45.

The signal ATDADx of a row address and page addresses ATDAD<0> and ATDAD<1> are input to the NAND circuit 40.

5 An output signal ATDMODE from the NAND circuit 40 is input to one input terminal of the NAND circuit 41.

The sense amplifier enable signal SAEBL that is time-serially generated by the internal CE control circuit 1 is supplied to the other input terminal of the NAND circuit 41. The output signal (reset signal  
10 R) from the NAND circuit 41 is input to one input terminal of the NAND circuit 42.

The ATD signal ATDSC of a column address output from the column system ATD 10 is supplied to the inverter 45. The output signal from the inverter 45 is  
15 supplied to one input terminal of the NAND circuit 43. The sense amplifier enable signal SAEBL is supplied to the other input terminal of the NAND circuit 43. The output signal (set signal S) from the NAND circuit 43 is supplied to one input terminal of the NAND  
20 circuit 44.

The output signal from the NAND circuit 42 is supplied to the other input terminal of the NAND circuit 44. The output signal from the NAND circuit 44 is supplied to the other input terminal of the NAND  
25 circuit 42. The mode determination signal SC is output from the NAND circuit 44.

The mode determination circuit 26 is an R-S

flip-flop circuit which uses the output from the NAND circuit 41 as the reset signal R and the output from the NAND circuit 43 as the set signal S. A column address transition after the sense amplifier enable signal SAEBL is activated is detected (set). The mode determination signal (column access determination signal) SC is changed to "H" level to start the column access mode. When a mode address (row address) is input next to consecutive column addresses, the mode determination signal SC is set at "L" level. It is determined that the column access mode is ended (reset), and the standby operation is started.

As the mode address, a row address is generally used. However, for example, a page address (A0/A1) used in a pseudo SRAM having a page mode may be used. Alternatively, a certain address may be defined as the mode address in advance and used.

When a certain address or page address is defined as the mode address of the end of column access in advance, the standby operation starts in accordance with the transition of the address. For this reason, it can be defined that the next cycle starts from the next transition of a row address or column address. Hence, the access time has no delay.

According to the specifications of this time, after the mode address defined as the column access end command is input, the standby operation is executed,

and the start address of the next cycle is then input.

As shown in FIGS. 14A and 14B, in the specifications in which a row address is used as the mode address, after the row address (mode address) is input as the column access end command, the standby operation is executed, and the start address (row or column) of the next cycle is then input, as in the case wherein a predetermined address is used as the mode address. However, even when the start address of the next cycle is a row address, the transition of the row address must occur twice.

As a modification to the above-described first embodiment, a row address may be input as the column access end command and the start address of the next cycle, as shown in FIGS. 15A and 15B. In this case, the next normal operation is generally defined as the start of the next cycle from the row address transition time. Since the active operation of the next cycle is being executed after the standby operation of the preceding cycle as the actual internal operation, the access time is delayed. However, it poses no problem because column access and row access are rarely mixed.

In this case, normally, the start address of the next cycle equals the mode address, and the start trigger of the next cycle is not generated. To cope with this situation, if no address transition is detected within a predetermined period after the end of

a precharge cycle (with constant time), it is regarded that the transition of the same address as the mode address has occurred. The pulse ATDSUM is automatically generated to start the next active cycle.

5           For example, as shown in FIGS. 15A and 15B, when the control signal CYCLE that defines the cycle changes to "L" level, and the preceding cycle is ended, a trigger according to the transition of the mode address is delayed by the trigger delay ON/OFF circuit 24 shown  
10           in FIG. 6, and a pulse is generated.

          According to this arrangement, since "mode address = start address of next cycle", the address transition need not be executed twice. However, there still exists the restriction in which the transition of  
15           the row address must occur to end column access. If the next cycle should be started in accordance with the transition of a column address, the transition of the mode address (row address) is executed first. After the standby operation, the transition of the column  
20           address must be executed.

          Especially, in the specifications compatible to the SRAM, the cycle time is regarded as important. The access time can be delayed. As for the cycle time, the precharge cycle is executed first, and then, the active  
25           cycle is executed. With this definition, time is not wasted in terms of specifications.

          When the above-described arrangement is employed,



the high-speed operation mode can reliably be executed in the asynchronous pseudo SRAM without adding any new control pins.

[Second Embodiment]

5           FIGS. 16 to 18 are views for explaining a semiconductor integrated circuit device according to the second embodiment of the present invention. FIG. 16 is a block diagram showing the detailed arrangement of a main part related to the read and  
10           write of a pseudo SRAM. FIGS. 17 and 18 are timing charts showing the operations of the pseudo SRAM. FIG. 17 shows the delayed normal write operation of the pseudo SRAM shown in FIG. 16. FIG. 18 shows the delayed static column write operation of the pseudo  
15           SRAM shown in FIG. 16.

          In the second embodiment of the present invention, as shown in FIG. 16, column access can be executed for an arrangement that includes the circuits according to the first embodiment shown in FIG. 6 and is also  
20           capable of coping with a delayed input of a write instruction.

          More specifically, a trigger delay ON/OFF circuit 28 is inserted between an AND circuit 4 and an ATD (transition detection circuit) 3d of an external write enable signal /WE. A write mode latch ON/OFF circuit  
25           20 is added to the output terminal of a first internal WE control circuit 6.

The trigger delay ON/OFF circuit 28 is used to receive the transition trigger of the external write enable signal /WE not within the cycle but after the end of the cycle.

5           The write mode latch ON/OFF circuit 20 is used to write data in a cell not in the current cycle but in the next cycle. An output signal INWE1 from the first internal WE control circuit 6 and an output signal PLCLK from a plate line control circuit 7 are supplied  
10           to the write mode latch ON/OFF circuit 20. An output signal INWE2 from a second internal WE control circuit 25 is generated and supplied to a data latch circuit 22. A first internal write enable signal INWE1 is supplied to an input/output system control circuit 17.

15           When this arrangement is employed, in the delayed normal write operation (the normal write of the delayed write) shown in FIG. 17, the write is detected as a write after the pulse driving of a plate line PL. Trigger generation in response to detection of the  
20           transition of the external write enable signal /WE is delayed until the end time of the cycle. On the basis of it, the internal chip enable signals INCE1 and INCE2 can be generated. Accordingly, the transition of the external write enable signal /WE, which has occurred  
25           in this cycle, can be detected as if it were the transition in the next cycle. A trigger can be generated in response to this transition, and the next

operation cycle can be started.

As write data, data during the cycle must be latched. Latch of write data to a write data latch 18 is executed by the input/output system control circuit 5 17 which receives the signal INWE1 generated on the basis of the external write enable signal /WE.

The above-described arrangement and operations will be summarized below.

The address transition occurs, and the cycle 10 starts. When the delayed write operation starts, the read operation is executed first. If the external write enable signal /WE changes to "L" level before the precharge of a plate line PL or word line WL starts (within the time defined by the internal timeout 15 circuit), control can be executed by the external write enable signal /WE. However, if the operation is so delayed that the write operation is started after the plate line PL ends pulse driving (after the plate line PL changes from "H" level to "L" level), the write 20 operation to the cell is not executed in this cycle although write data during the cycle is latched. The next cycle is automatically activated, and the write operation to the cell is executed in the next cycle.

When the external write enable signal /WE changes 25 from "L" level to "H" level during the write operation of the internal WE control circuit, the write operation is ended. To prevent this, once the internal circuits

start the write operation, the internal write enable signal INWE1 having a predetermined width is generated to hold the write operation for a predetermined time. When the above-described arrangement is employed, the user can freely execute the write operation even in the asynchronous pseudo SRAM.

The column access operation of the device having the above arrangement will be described next with reference to the timing chart shown in FIG. 17.

The operation until the write operation starts is the same as the normal operation. When the delayed write operation starts, the write operation to the cell is not executed in that cycle. The next cycle is automatically activated to start the internal operation cycle. Then, after a sense amplifier enable signal SAEBL is activated, the transition of the column address is detected. A mode determination circuit 26 determines that column access starts. A column access determination signal SC is changed to "H" level to start the column access mode. When a mode address (row address) is input next to consecutive column addresses, the column access determination signal SC is set at "L" level. It is determined that the column access mode is ended, and the standby operation is started.

At this time, the second internal write enable signal INWE of the second internal WE control circuit 25 maintains "H" level to latch the write mode until

the column access is ended. Even when the arrangement without any restriction in the write operation is employed, column access can be executed.

[Third Embodiment]

5           FIG. 19 is a block diagram for explaining a semiconductor integrated circuit device according to the third embodiment of the present invention. In this embodiment, byte control can be executed. When byte control is executed for, e.g., a 16-bit semiconductor  
10           device, the bits are divided into lower 8 bits (LB) and upper 8 bits (UB). A read or write can be executed in a lump for the lower or upper bits. Byte control is used when, for example, a 16-bit structure is to be used as if it were an 8-bit structure, or lower and  
15           upper bits should be separately read- or write-accessed.

          To implement such byte control, same circuits related to byte control in the above-described second embodiment are prepared as two systems for lower bits  
20           (LB) and upper bits (UB).

          The same reference numerals as in FIG. 16 denote the same parts in FIG. 19. For circuits for lower bits, "A" is added to the reference numerals used in FIG. 16. For circuits for upper bits, "B" is added to  
25           the reference numerals used in FIG. 16.

          The operations of the circuits shown in FIG. 19 are basically the same as in the circuits shown in

FIG. 16 except that a read or write is executed for the lower or upper bits, and a detailed description thereof will be omitted.

[Fourth Embodiment]

5           In the semiconductor integrated circuit devices according to the first to third embodiments, pseudo SRAMs have been described, which use, in the memory core portion, an array of ferroelectric cells MC1 each having a 1-transistor/1-capacitor structure and  
10           independently connected to the bit line BL and plate line PL. However, the present invention can also be applied to a pseudo SRAM which uses, in the memory core portion, an array in which a unit of TC parallel unit series-connected ferroelectric cells is connected to a  
15           bit line BL and plate line PL.

FIGS. 20A and 20B are, respectively, an equivalent circuit diagram of one unit of TC parallel unit series-connected ferroelectric cells and its operation waveforms.

20           In one unit of TC parallel unit series-connected ferroelectric cells shown in FIG. 20A, the current paths between a plurality of (in this example, four) ferroelectric cells MC2-0 to MC2-3 and one unit select transistor ST are connected in series between a bit  
25           line BL and a plate line PL. Each of the ferroelectric cells MC2-0 to MC2-3 is constituted by connecting the current path of a cell transistor T2 and a

ferroelectric capacitor C2 in parallel. The gates of the cell transistors T2 of the ferroelectric cells MC2-0 to MC2-3 are connected to word lines WL0 to WL3, respectively. The gate of the unit select transistor ST is connected to a unit select line BS.

Of the word lines WL0 to WL3, word lines except ones corresponding to the selected ferroelectric cell are set at "H" level. The cell transistors corresponding to these word lines are controlled to the ON state. Only one word line corresponding to the selected ferroelectric cell is set at "L" level. The cell transistor corresponding to this word line is controlled to the OFF state. One electrode of the cell capacitor of the selected ferroelectric cell is connected to the bit line BL. The other electrode is connected to the plate line PL.

Even with the above-described cell structure, almost the same functions and effects as in the above-described pseudo SRAMs which use, in the memory core portion, ferroelectric cells each having a 1-transistor/1-capacitor structure can basically be obtained.

#### [Fifth Embodiment]

In the semiconductor integrated circuit devices according to the first to fourth embodiments, pseudo SRAMs have been described, which use, in the memory core portion, the ferroelectric cells MC1 and MC2 each

of which pulse-drives the potential of the plate line PL, as shown in FIGS. 7A and 20A.

In the fifth embodiment, DRAM cells each having a 1-transistor/1-capacitor structure are used in the memory core portion.

More specifically, DRAM cells MC3 each having a 1-transistor/1-capacitor structure shown in FIG. 21A are arranged in a matrix in a memory cell array 16. One end of the current path of a cell transistor T3 is connected to a bit line BL. The other end is connected to one electrode of a cell capacitor C3. The other electrode of the cell capacitor C3 is connected to a plate line PL.

As shown in FIG. 21B, the precharge voltage of the bit line BL and the potential of the plate line PL are set to  $1/2$  a power supply voltage VCC. In this state, a word line WL is selected.

Even with the above-described structure, almost the same functions and effects as in the pseudo SRAMs described in the first to fourth embodiments, which use, in the memory core portion, the ferroelectric cells MC1 or MC2, can basically be obtained.

As described above, the semiconductor integrated circuit device including the pseudo SRAM of each embodiment of the present invention can cope with both the asynchronous operation and the high-speed operation mode such as a static column mode, unlike the prior



art. In addition, even in the arrangement without any restriction in the write operation, a high-speed operation mode can be implemented.

5 The semiconductor integrated circuit devices according to the above-described first to fifth embodiments of the present invention can be applied to various apparatuses in place of existing SRAMs. Especially, the semiconductor integrated circuit devices according to the first to fourth embodiments  
10 use a ferroelectric memory in the memory core portion and can be applied to, e.g., optional memories of various types or cards which store media contents by using nonvolatility. FIGS. 22 to 24 show application examples.

15 (Application Example 1)

FIG. 22 shows the DSL (Digital Subscriber Line) data path portion of a DSL modem. This modem includes a programmable digital signal processor (DSP) 110, analog/digital (A/D) converter 120, digital/analog  
20 (D/A) converter 130, transmission driver 150, and receiver amplifier 160. FIG. 22 does not illustrate a bandpass filter. Instead, a pseudo SRAM 170 according to one of the embodiments and an EEPROM 180 are illustrated as optional memories of various types to  
25 hold a line code program (a program which is executed by the DSP to select and operate a modem in accordance with encoded subscriber line information and

transmission conditions (line code; QAM, CAP, RSK, FM, AM, PAM, DWMT, and the like)).

In Application Example 1, two kinds of memories, i.e., the pseudo SRAM 170 and EEPROM 180 are used as memories to hold the line code program. The EEPROM 180 may be replaced with a pseudo SRAM. That is, instead of using two types of memories, only pseudo SRAMs may be used.

(Application Example 2)

FIG. 23 shows a cellular phone terminal 300 as another application example. A communication section 200 which implements a communication function comprises a transmitting/receiving antenna 201, an antenna shared section 202, a receiver section 203, a baseband processing section 204, a DSP 205 used as a voice codec, a loudspeaker (receiver) 206, a microphone (transmitter) 207, a transmitter section 208, and a frequency synthesizer 209.

The cellular phone terminal 300 has a control section 220 which controls the sections of the cellular phone terminal. The control section 220 is a microcomputer which is formed by connecting a CPU 221, a ROM 222, a pseudo SRAM 223 according to one of the embodiments, and a flash memory 224 through a CPU bus 225. The ROM 222 stores, in advance, a program to be executed by the CPU 221 and necessary data such as fonts to be displayed. The pseudo SRAM 223 is mainly

used as a work area where the CPU 221 stores, as  
needed, data midway through calculation during  
executing the program, or data exchanged between the  
control section 220 and the respective sections are  
5 temporarily stored. Even when the cellular phone  
terminal 300 is powered off, the flash memory 224  
stores, e.g., the immediately preceding set conditions,  
so the same set conditions can be used when the  
cellular phone terminal is powered on again.  
10 Accordingly, even when the cellular phone terminal is  
powered off, the stored set parameters are not erased.

The cellular phone terminal 300 also has an audio  
reproduction processing section 211, an external output  
terminal 212, an LCD (Liquid Crystal Display)  
15 controller 213, an LCD 214 for display, and a ringer  
215 which generates a ringing signal. The audio  
reproduction processing section 211 reproduces audio  
information input to the cellular phone terminal 300  
(or audio information stored in an external memory 240  
20 (to be described later)). The audio information that  
is reproduced can be transmitted to a headphone or a  
portable loudspeaker through the external output  
terminal 212 and extracted to the outside. When the  
audio reproduction processing section 211 is prepared,  
25 audio information can be reproduced. The LCD  
controller 213 receives display information from, e.g.,  
the CPU 221 through the CPU bus 225, converts the

display information into LCD control information to control the LCD 214, and drives the LCD 214 to cause it to perform display.

5       The cellular phone terminal 300 also has interface circuits (I/Fs) 231, 233, and 235, the external memory 240, an external memory slot 232, a key operation section 234, and an external input/output terminal 236. The external memory slot 232 receives the external memory 240 such as a memory card. The external memory  
10       slot 232 is connected to the CPU bus 225 through the interface circuit (I/F) 231. As described above, when the slot 232 is prepared in the cellular phone terminal 300, information in the cellular phone terminal 300 can be written in the external memory 240. Alternatively,  
15       information (e.g., audio information) stored in the external memory 240 can be input to the cellular phone terminal 300. The key operation section 234 is connected to the CPU bus 225 through the interface circuit (I/F) 233. Key input information input from  
20       the key operation section 234 is transmitted to, e.g., the CPU 221. The external input/output terminal 236 is connected to the CPU bus 225 through the interface circuit (I/F) 233 and functions as a terminal in inputting various kinds of external information to the  
25       cellular phone terminal 300 or outputting information externally from the cellular phone terminal 300.

      In Application Example 2, the ROM 222, pseudo SRAM

223, and flash memory 224 are used. Since the flash memory 224 is nonvolatile, it may be replaced with a pseudo SRAM. The ROM 222 may also be replaced with a pseudo SRAM.

5 (Application Example 3)

FIG. 24 shows an example in which a pseudo SRAM is applied to a card as a smart medium which stores media contents.

A card main body 400 incorporates a pseudo SRAM  
10 chip 401. An opening portion 402 is formed in the card main body 400 at a position corresponding to the pseudo SRAM chip 401 so the pseudo SRAM chip 401 is exposed. The opening portion 402 has a shutter 403. When the card is carried, the pseudo SRAM chip 401 is protected  
15 by the shutter 403. When data is to be written, the shutter 403 is opened to expose the pseudo SRAM chip 401. An external terminal 404 is used to extract content data stored in the card. If the number of external terminals 404 is not limited, data may be  
20 written through only the external terminals 404 without forming the opening portion 402 at the position corresponding to the pseudo SRAM chip 401.

According to the arrangements of Application Examples 1 to 3, the advantages of the pseudo SRAM,  
25 i.e., no limit on address input, low power consumption, an asynchronous operation for an external input signal, a relatively high operation speed, and nonvolatility

can be effectively used.

A pseudo SRAM has been exemplified above as a semiconductor integrated circuit device. However, the present invention can also be applied to a semiconductor integrated circuit device in which a pseudo SRAM and logic circuit are embedded, or a semiconductor integrated circuit device called a SOC in which a system is mounted in one chip.

As described above, according to one aspect of this invention, a semiconductor integrated circuit device which can flexibly execute both an asynchronous operation and a high-speed operation mode without being limited by the cycle time in a predetermined range can be obtained.

Additional advantages and modifications will readily occur to those skilled in the art. Therefore, the invention in its broader aspects is not limited to the specific details and representative embodiments shown and described herein. Accordingly, various modifications may be made without departing from the spirit or scope of the general inventive concept as defined by the appended claims and their equivalents.